

Data sheet acquired from Harris Semiconductor SCHS177B

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High-Speed CMOS Logic Digital Phase-Locked Loop

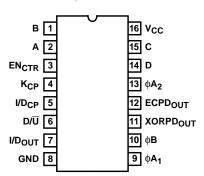
Features

- Digital Design Avoids Analog Compensation Errors
- Easily Cascadable for Higher Order Loops
- Useful Frequency Range
 - K-Clock......DC to 55MHz (Typ)
 - I/D-Clock DC to 35MHz (Typ)
- Dynamically Variable Bandwidth
- · Very Narrow Bandwidth Attainable
- Power-On Reset
- Output Capability
 - Standard......XORPD_{OUT}, ECPD_{OUT}
 - Bus Driver......I/D_{OUT}
- Fanout (Over Temperature Range)

 - Bus Driver Outputs 15 LSTTL Loads
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- 'HC297 Types
 - Operation Voltage 2 to 6V
 - High Noise Immunity N_{IL} = 30%, N_{IH} = 30% of V_{CC} at 5V
- CD74HCT297 Types
 - Operation Voltage 4.5 to 5.5V
 - Direct LSTTL Input Logic Compatibility
 V_{IL} = 0.8V (Max), V_{IH} = 2V (Min)
 - CMOS Input Compatibility I $_I \leq 1 \mu A$ at $V_{OL},\,V_{OH}$

Pinout

CD54HC297 (CERDIP) CD74HC297, CD74HCT29 (PDIP) TOP VIEW



Description

The 'HC297 and CD74HCT297 are high-speed silicon gate CMOS devices that are pin-compatible with low power Schottky TTL (LSTTL).

These devices are designed to provide a simple, cost-effective solution to high-accuracy, digital, phase-locked-loop applications. They contain all the necessary circuits, with the exception of the divide-by-N counter, to build first-order phase-locked-loops.

Both EXCLUSIVE-OR (XORPD) and edge-controlled phase detectors (ECPD) are provided for maximum flexibility. The input signals for the EXCLUSIVE-OR phase detector must have a 50% duty factor to obtain the maximum lock-range.

Proper partitioning of the loop function, with many of the building blocks external to the package, makes it easy for the designer to incorporate ripple cancellation (see Figure 2) or to cascade to higher order phase-locked-loops.

The length of the up/down K-counter is digitally programmable according to the K-counter function table. With A, B, C and D all LOW, the K-counter is disabled. With A HIGH and B, C and D LOW, the K-counter is only three stages long, which widens the bandwidth or capture range and shortens the lock time of the loop. When A, B, C and D are all programmed HIGH, the K-counter becomes seventeen stages long, which narrows the bandwidth or capture range and lengthens the lock time. Real-time control of loop bandwidth by manipulating the A to D inputs can maximize the overall performance of the digital phase-locked-loop.

The 'HC297 and CD74HCT297 can perform the classic first order phase-locked-loop function without using analog components. The accuracy of the digital phase-locked-loop (DPLL) is not affected by $V_{\rm CC}$ and temperature variations but depends solely on accuracies of the K-clock and loop propagation delays.

Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE		
CD54HC297F3A	-55 to 125	16 Ld CERDIP		
CD74HC297E	-55 to 125	16 Ld PDIP		
CD74HCT297E	-55 to 125	16 Ld PDIP		

The phase detector generates an error signal waveform that, at zero phase error, is a 50% duty factor square wave. At the limits of linear operation, the phase detector output will be either HIGH or LOW all of the time depending on the direction of the phase error (ϕ IN - ϕ OUT). Within these limits the phase detector output varies linearly with the input phase error according to the gain K_d , which is expressed in terms of phase detector output per cycle or phase error. The phase detector output can be defined to vary between ± 1 according to the relation:

phase detector output =
$$\frac{\text{%HIGH - %LOW}}{100}$$

The output of the phase detector will be $K_d\phi_e$, where the phase error $\phi_e=\phi IN$ - ϕOUT .

EXCLUSIVE-OR phase detectors (XORPD) and edge-controlled phase detectors (ECPD) are commonly used digital types. The ECPD is more complex than the XORPD logic function but can be described generally as a circuit that changes states on one of the transitions of its inputs. The gain (K_d) for an XORPD is 4 because its output remains HIGH (XORPD_{OUT} = 1) for a phase error of one quarter cycle.

Similarly, K_d for the ECPD is 2 since its output remains HIGH for a phase error of one half cycle. The type of phase detector will determine the zero-phase-error point, i.e., the phase separation of the phase detector inputs for a ϕ e defined to be zero. For the basic DPLL system of Figure 3, ϕ e = 0 when the phase detector output is a square wave.

The XORPD inputs are one quarter cycle out-of-phase for zero phase error. For the ECPD, $\phi e = 0$ when the inputs are one half cycle out of phase.

The phase detector output controls the up/down input to the K-counter. The counter is clocked by input frequency M_{C} which is a multiple M of the loop center frequency $f_{C}.$ When the K-counter recycles up, it generates a carry pulse. Recycling while counting down generates a borrow pulse. If the carry and the borrow outputs are conceptually combined into one output that is positive for a carry and negative for a borrow, and if the K-counter is considered as a frequency divider with the ratio Mf_{C}/K , the output of the K-counter will equal the input frequency multiplied by the division ratio. Thus the output from the K-counter is $(K_{\rm d}\varphi_{\rm e}Mf_{\rm C})/K$.

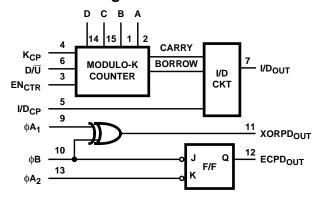
The carry and borrow pulses go to the increment/decrement (I/D) circuit which, in the absence of any carry or borrow pulses has an output that is one half of the input clock (I/D_{CP}). The input clock is just a multiple, 2N, of the loop center frequency. In response to a carry of borrow pulse, the I/D circuit will either add or delete a pulse at I/D_{OUT}. Thus the output of the I/D circuit will be Nf_C + ($K_d\phi_eMf_c$)/2K.

The output of the N-counter (or the output of the phase-locked-loop) is thus: $f_0 = f_C + (K_d \phi_e M f_C)/2KN$.

If this result is compared to the equation for a first-order analog phase-locked-loop, the digital equivalent of the gain of the VCO is just $Mf_c/2KN$ or f_c/K for M = 2N.

Thus, the simple first-order phase-locked-loop with an adjustable K-counter is the equivalent of an analog phase-lockedloop with a programmable VCO gain.

Functional Diagram



FUNCTION TABLE EXCLUSIVE-OR PHASE DETECTOR

φ Α 1	φВ	XORPD OUT
L	L	L
L	Н	Н
Н	L	Н
Н	Н	L

FUNCTION TABLE EDGE-CONTROLLED PHASE DETECTOR

φ Α 2	φВ	ECPD OUT
H or L	\	Н
\	H or L	L
H or L	↑	No Change
↑	H or L	No Change

H = Steady-State High Level, L = Steady-State Low Level, \uparrow = LOW to HIGH ϕ Transition, \downarrow = HIGH to LOW ϕ Transition

K-COUNTER FUNCTION TABLE (DIGITAL CONTROL)

D	С	В	Α	MODULO (K)
L	L	L	L	Inhibited
L	L	L	Н	2 ³
L	L	Н	L	2 ⁴
L	L	Н	Н	2 ⁵
L	Н	L	L	2 ⁶
L	Н	L	Н	2 ⁷
L	Н	Н	L	2 ⁸
L	Н	Н	Н	2 ⁹
Н	L	L	L	2 ¹⁰
Н	L	L	Н	2 ¹¹
Н	L	Н	L	2 ¹²
Н	L	Н	Н	2 ¹³
Н	Н	L	L	2 ¹⁴
Н	Н	L	Н	2 ¹⁵
Н	Н	Н	L	2 ¹⁶
Н	Н	Н	Н	2 ¹⁷

Absolute Maximum Ratings

DC Supply Voltage, V_{CC} -0.5V to 7V DC Input Diode Current, I_{IK} For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$ ± 20 mA DC Output Diode Current, IOK For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$±20mA DC Drain Current, per Output, IO For $-0.5V < V_O < V_{CC} + 0.5V$±25mA DC Output Source or Sink Current per Output Pin, IO

Thermal Information

Thermal Resistance (Typical, Note 1)	θ_{JA} (°C/W)
E (PDIP) Package	67
Maximum Junction Temperature	150 ⁰ C
Maximum Storage Temperature Range	65°C to 150°C
Maximum Lead Temperature (Soldering 10s)	300°C

Operating Conditions

Temperature Range, T _A 55°C to 125°C
Supply Voltage Range, V _{CC}
HC Types2V to 6V
HCT Types
DC Input or Output Voltage, V _I , V _O 0V to V _{CC}
Input Rise and Fall Time
2V
4.5V 500ns (Max)
6V

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. The package thermal impedance is calculated in accordance with JESD 51-7.

DC Electrical Specifications

		TEST CONDITIONS			25°C			-40°C T	O 85°C	-55°C T	O 125°C				
PARAMETER	SYMBOL	V _I (V)	I _O (mA)	v _{cc} (v)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS			
HC TYPES															
High Level Input	V _{IH}	-	-	2	1.5	-	-	1.5	-	1.5	-	V			
Voltage				4.5	3.15	-	-	3.15	-	3.15	-	V			
				6	4.2	-	-	4.2	-	4.2	-	٧			
Low Level Input	V _{IL}	-	-	2	-	-	0.5	-	0.5	-	0.5	٧			
Voltage				4.5	-	-	1.35	-	1.35	-	1.35	٧			
				6	-	-	1.8	-	1.8	-	1.8	٧			
High Level Output	VoH	V _{IH} or V _{IL}	-0.02	2	1.9	-	-	1.9	-	1.9	-	٧			
Voltage CMOS Loads			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V			
							-0.02	6	5.9	-	-	5.9	-	5.9	-
High Level Output Voltage			-6 (Note 2)	4.5	3.98	-	-	3.84	-	3.7	-	V			
TTL Loads			-7.8 (Note 2)	6	5.48	-	-	5.34	-	5.2	-	V			
Low Level Output	V _{OL}	V _{IH} or	0.02	2	-	-	0.1	-	0.1	-	0.1	V			
Voltage CMOS Loads		V_{IL}	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V			
			0.02	6	-	-	0.1	-	0.1	-	0.1	٧			
Low Level Output Voltage			4 (Note 2)	4.5	-	-	0.26	-	0.33	-	0.4	V			
TTL Loads			5.2 (Note 2)	6	=	-	0.26	-	0.33	-	0.4	V			

DC Electrical Specifications (Continued)

			ST ITIONS			25°C			O 85°C	-55°C T	O 125°C	
PARAMETER	SYMBOL	V _I (V)	I _O (mA)	V _{CC} (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
Input Leakage Current	lı	V _{CC} or GND	-	6	-	-	±0.1	-	±1	-	±1	μА
Quiescent Device Current	Icc	V _{CC} or GND	0	6	-	-	8	-	80	-	160	μА
HCT TYPES												
High Level Input Voltage	V _{IH}	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V _{IL}	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V _{OH}	V _{IH} or V _{IL}	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V _{OL}	V _{IH} or V _{IL}	0.02	4.5	-	-	0.1	-	0.1	-	0.1	٧
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	lı	V _{CC} to GND	0	5.5	-	-	±0.1	-	±1	-	±1	μА
Quiescent Device Current	Icc	V _{CC} or GND	0	5.5	-	-	8	-	80	-	160	μА
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI _{CC} (Note 2)	V _{CC} -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	μА

NOTE:

HCT Input Loading Table

INPUT	UNIT LOADS
EN _{CTR} , D/Ū	0.3
A, B, C, D, K _{CP} , φA ₂	0.6
I/D _{CP} , φA ₁ , φB	1.5

NOTE: Unit Load is ΔI_{CC} limit specified in DC Electrical Specifications table, e.g., 360 μA max at 25 $^{o}\text{C}.$

^{2.} For dual-supply systems theoretical worst case ($V_I = 2.4V$, $V_{CC} = 5.5V$) specification is 1.8mA.

Prerequisite For Switching Function

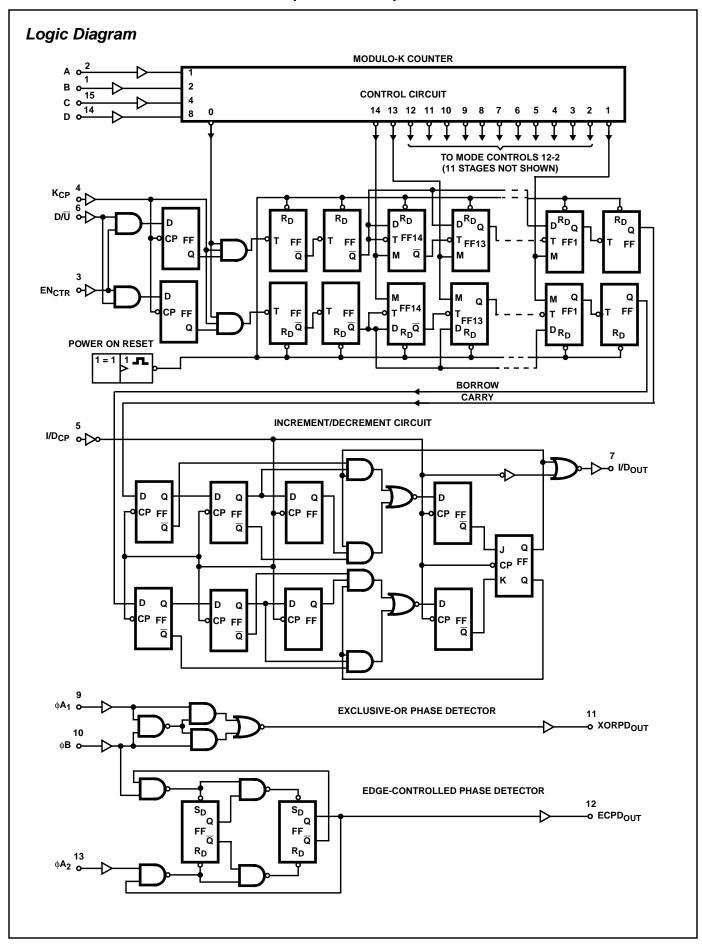
			25	°C	-40°C T	O 85°C	-55°C T	O 125°C	
PARAMETER	SYMBOL	V _{CC} (V)	MIN	MAX	MIN	MAX	MIN	MAX	UNITS
HC TYPES									
Maximum Clock Frequency	f _{MAX}	2	6	-	5	-	4	-	MHz
K _{CP}		4.5	30	-	24	-	20	-	MHz
		6	35	-	28	-	24	-	MHz
Maximum Clock Frequency	f _{MAX}	2	4	-	3	ı	2	-	MHz
I/D _{CP}		4.5	20	-	16	ı	13	-	MHz
		6	24	-	19	-	15	-	MHz
Clock Pulse Width	t _w	2	80	-	100	-	120	-	ns
K _{CP}		4.5	16	-	20	-	24	-	ns
		6	14	-	17	-	20	-	ns
Clock Pulse Width	t _W	2	125	-	155	-	190	-	ns
I/D _{CP}		4.5	25	-	31	-	38	-	ns
		6	21	-	26	-	32	-	ns
Set-up Time	tsu	2	100	-	125	-	150	-	ns
D/\overline{U} , EN_{CTR} to K_{CP}		4.5	20	-	25	-	30	-	ns
		6	17	-	21	-	26	-	ns
Hold Time	t _H	2	0	-	0	-	0	-	ns
D/\overline{U} , EN_{CTR} to K_{CP}		4.5	0	-	0	-	0	-	ns
		6	0	-	0	-	0	-	ns
HCT TYPES									
Maximum Clock Frequency K _{CP}	f _{MAX}	4.5	30	-	24	-	20	-	MHz
Maximum Clock Frequency I/D _{CP}	f _{MAX}	4.5	20	-	16	-	13	-	MHz
Clock Pulse Width K _{CP}	t _w	4.5	16	-	20	-	24	-	ns
Clock Pulse Width I/D _{CP}	t _w	4.5	25	-	31	-	38	-	ns
Set-up Time D/\overline{U} , EN_{CTR} to K_{CP}	t _{SU}	4.5	20	-	25	-	30	-	ns
Hold Time D/\overline{U} , EN_{CTR} to K_{CP}	t _H	4.5	0	-	0	-	0	-	ns

Switching Specifications Input t_r , $t_f = 6 \text{ns}$

		TEST		25°C		-40°C TO 85°C	-55°C TO 125°C	
PARAMETER	PARAMETER SYMBOL		V _{CC} (V)	TYP	MAX	MAX	MAX	UNITS
HC TYPES								
Propagation Delay,	t _{PLH} , t _{PHL}	C _L = 50pF	2	1	175	220	265	ns
I/D _{CP} to I/D _{OUT}			4.5	-	35	44	53	ns
			6	-	30	34	43	ns

Switching Specifications Input t_r , t_f = 6ns (Continued)

		TEST		25	°C	-40°C TO 85°C	-55°C TO 125°C		
PARAMETER	SYMBOL	CONDITIONS	V _{CC} (V)	TYP MAX		MAX	MAX	UNITS	
Propagation Delay,	t _{PLH} , t _{PHL}	C _L = 50pF	2	-	150	190	225	ns	
φA ₁ , φB to XORPD _{OUT}			4.5	=	30	38	45	ns	
			6	-	26	33	38	ns	
Propagation Delay,	t _{PHL} , t _{PHL}	C _L = 50pF	2	-	200	250	300	ns	
$\phi B, \phi A_2$ to ECPD _{OUT}			4.5	=	40	50	60	ns	
			6	-	34	43	51	ns	
Output Transition Time	t _{TLH}	C _L = 50pF	2	=	75	95	110	ns	
XORPD _{OUT} ECPD _{OUT}			4.5	=	15	19	22	ns	
			6	=	13	16	19	ns	
Output Transition Time	t _{TLH}	C _L = 50pF	2	=	60	75	90	ns	
I/D _{OUT}			4.5	=	12	15	18	ns	
			6	=	10	13	15	ns	
Input Capacitance	CI	-	-	=	10	10	10	pF	
HCT TYPES	•								
Propagation Delay, I/D _{CP} to I/D _{OUT}	tpLH, tpHL	C _L = 50pF	4.5	-	35	44	53	ns	
Propagation Delay, φA ₁ , φB to XORPD _{OUT}	t _{PLH} , t _{PHL}	C _L = 50pF	4.5	-	30	38	45	ns	
Propagation Delay, φB, φA ₂ to ECPD _{OUT}	t _{PHL} , t _{PHL}	C _L = 50pF	4.5	-	40	50	60	ns	
Output Transition Time XORPD _{OUT}	t _{TLH}	C _L = 50pF	4.5	-	15	19	22	ns	
Output Transition Time ECPD _{OUT}	t _{TLH}	C _L = 50pF	4.5	-	12	15	18	ns	
Input Capacitance	Cl	-	-	-	10	10	10	pF	



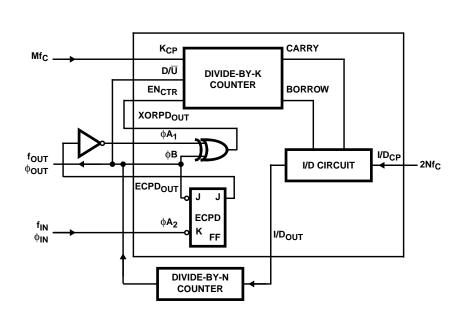


FIGURE 1. DPLL USING BOTH PHASE DETECTORS IN A RIPPLE-CANCELLATION SCHEME

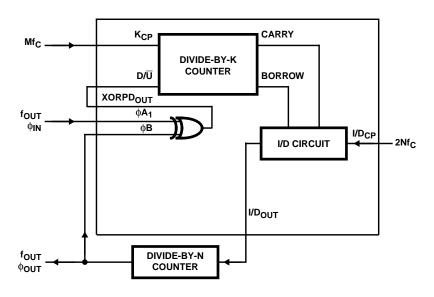


FIGURE 2. DPLL USING EXCLUSIVE-OR PHASE DETECTION

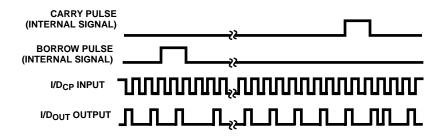


FIGURE 3. TIMING DIAGRAM: I/DOUT IN-LOCK CONDITION

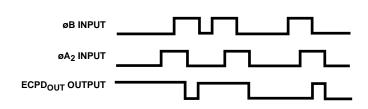


FIGURE 4. TIMING DIAGRAM: EDGE CONTROLLED PHASE COMPARATOR WAVEFORMS

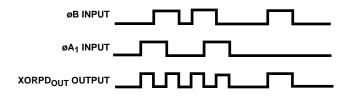


FIGURE 5. TIMING DIAGRAM: EXCLUSIVE OR PHASE DETECTOR WAVEFORMS

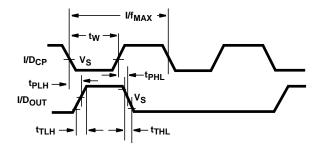


FIGURE 6. WAVEFORMS SHOWING THE CLOCK (I/D $_{
m CP}$) TO OUTPUT (I/D $_{
m OUTP}$) PROPAGATION DELAYS, CLOCK PULSE WIDTH, OUTPUT TRANSITION TIMES AND MAXIMUM CLOCK PULSE FREQUENCY

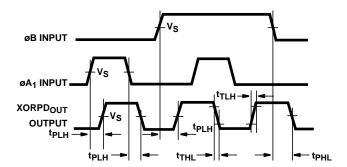


FIGURE 7. WAVEFORMS SHOWING THE PHASE INPUT ($\emptyset B$, $\emptyset A_1$) TO OUTPUT (XORPD $_{OUT}$) PROPAGATION DELAYS AND OUTPUT TRANSITION TIMES

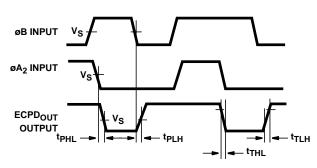
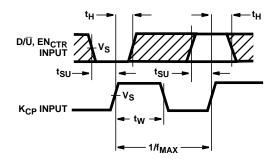


FIGURE 8. WAVEFORMS SHOWING THE PHASE INPUT ($\emptyset B$, $\emptyset A_2$) TO OUTPUT (ECPD $_{OUT}$) PROPAGATION DELAYS AND OUTPUT TRANSITION TIMES



NOTE: The shaded areas indicate when the input is permitted to change for predictable output performance.

FIGURE 9. WAVEFORMS SHOWING THE CLOCK (KCP) PULSE WIDTH AND MAXIMUM CLOCK PULSE FREQUENCY, AND THE INPUT (D/ $\overline{\rm U}$, ENCTR) TO CLOCK (KCP) SETUP AND HOLD TIMES

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8999001EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8999001EA CD54HC297F3A	Samples
CD54HC297F3A	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8999001EA CD54HC297F3A	Samples
CD74HC297E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC297E	Samples
CD74HC297EE4	ACTIVE	PDIP	N	16	25	TBD	Call TI	Call TI	-55 to 125		Samples
CD74HCT297E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT297E	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

PACKAGE OPTION ADDENDUM

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OTHER QUALIFIED VERSIONS OF CD54HC297, CD74HC297:

Catalog: CD74HC297

Military: CD54HC297

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD74HC297E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC297E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT297E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT297E	N	PDIP	16	25	506	13.97	11230	4.32

14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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